

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
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EPAS ID: PAT4516528

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
KINAM SONG	07/24/2017
WONHI OH	07/24/2017
JINKYU CHOI	07/24/2017
JUNHO LEE	07/24/2017
SEUNGHYUN HONG	07/24/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
<b>Street Address:</b>	5005 E. MCDOWELL ROAD
<b>Internal Address:</b>	MAILDROP A700
<b>City:</b>	PHOENIX
<b>State/Country:</b>	ARIZONA
<b>Postal Code:</b>	85008
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15657406
<b>CORRESPONDENCE DATA</b>	
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<b>Correspondent Name:</b>	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
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<b>ATTORNEY DOCKET NUMBER:</b>	FSC75527US
<b>NAME OF SUBMITTER:</b>	SHARRON CASTILLO
<b>SIGNATURE:</b>	/Sharron Castillo/
<b>DATE SIGNED:</b>	07/24/2017

**Total Attachments: 3**

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## ASSIGNMENT & AGREEMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we,

Name	of (City and State OR Country)
KINAM SONG	SEOUL KOREA, REPUBLIC OF
WONHI OH	BUCHEON KOREA, REPUBLIC OF
JINKYU CHOI	BUCHEON KOREA, REPUBLIC OF
JUNHO LEE	BUCHEON KOREA, REPUBLIC OF
SEUNGHYUN HONG	SEOUL KOREA, REPUBLIC OF

agree to sell, assign, and transfer, and do hereby sell, assign, and transfer to Semiconductor Components Industries, LLC, a limited liability company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives ("SCI"), the entire right, title, and interest in and to the inventions and discoveries as described, illustrated, and/or claimed in

**Title: DRIVE CIRCUIT FOR POWER SEMICONDUCTOR DEVICES**

**Attorney Docket No.: FSC75527US**

**Serial No.:** 15/657406

**Filing Date:** July 24, 2017

together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

We further authorize SCI to apply for and hold and maintain the Patent Rights throughout the world directly in its own name or any other name which SCI deems appropriate in its sole discretion, and to claim the priority of the filing date of the above listed application(s).

We agree that, when requested, we will, without charge to SCI, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing, maintaining, and enforcing the Patent Rights in any and all countries and for vesting title thereto in SCI or its nominees.

We represent and warrant that we have full right to convey the entire right, title and interest herein sold, assigned, and transferred, and that the Patent Rights hereby conveyed are free from all prior assignment, grant, mortgage, license, or other encumbrance to anyone other than SCI. We covenant and further warrant that we will not convey hereafter any part of the Patent Rights to anyone other than SCI or do any act whatsoever conflicting with this ASSIGNMENT & AGREEMENT.

We hereby authorize SCI or anyone it may properly designate to insert in this ASSIGNMENT & AGREEMENT the filing date and serial number of the above listed application(s) when ascertained. More than one counterpart of this ASSIGNMENT & AGREEMENT may be executed, each of which will be deemed an original.

By (Inventor signature): Kinam Song  
Kinam Song

Witnessed by (Witness signature): [Signature]

Printed name of Witness: SangEui Han

Signed and Witnessed on (date): 2017/7/24

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By (Inventor signature): Wonhi Oh  
Wonhi Oh

Witnessed by (Witness signature): [Signature]

Printed name of Witness: SangEui Han

Signed and Witnessed on (date): 2017/9/24

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By (Inventor signature): JIN KYU CHOI  
Jinkyu Choi

Witnessed by (Witness signature): [Signature]

Printed name of Witness: SangEui Han

Signed and Witnessed on (date): 2017/9/24

By (Inventor signature): Jun Mo Lee  
JunMo Lee

Witnessed by (Witness signature): [Signature]

Printed name of Witness: Sang Eun Han

Signed and Witnessed on (date): 2017/7/24

By (Inventor signature): Seunghyun Hong  
Seunghyun Hong

Witnessed by (Witness signature): [Signature]

Printed name of Witness: Sang Eun Han

Signed and Witnessed on (date): 2017/7/24